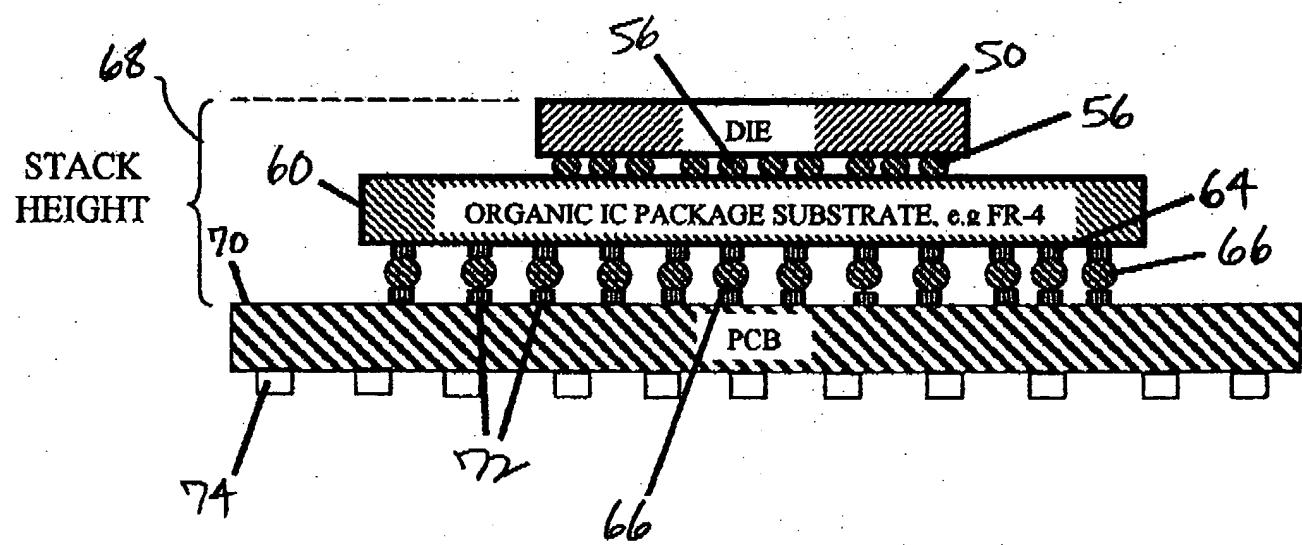


FIG. 1



**FIG. 2
(PRIOR ART)**

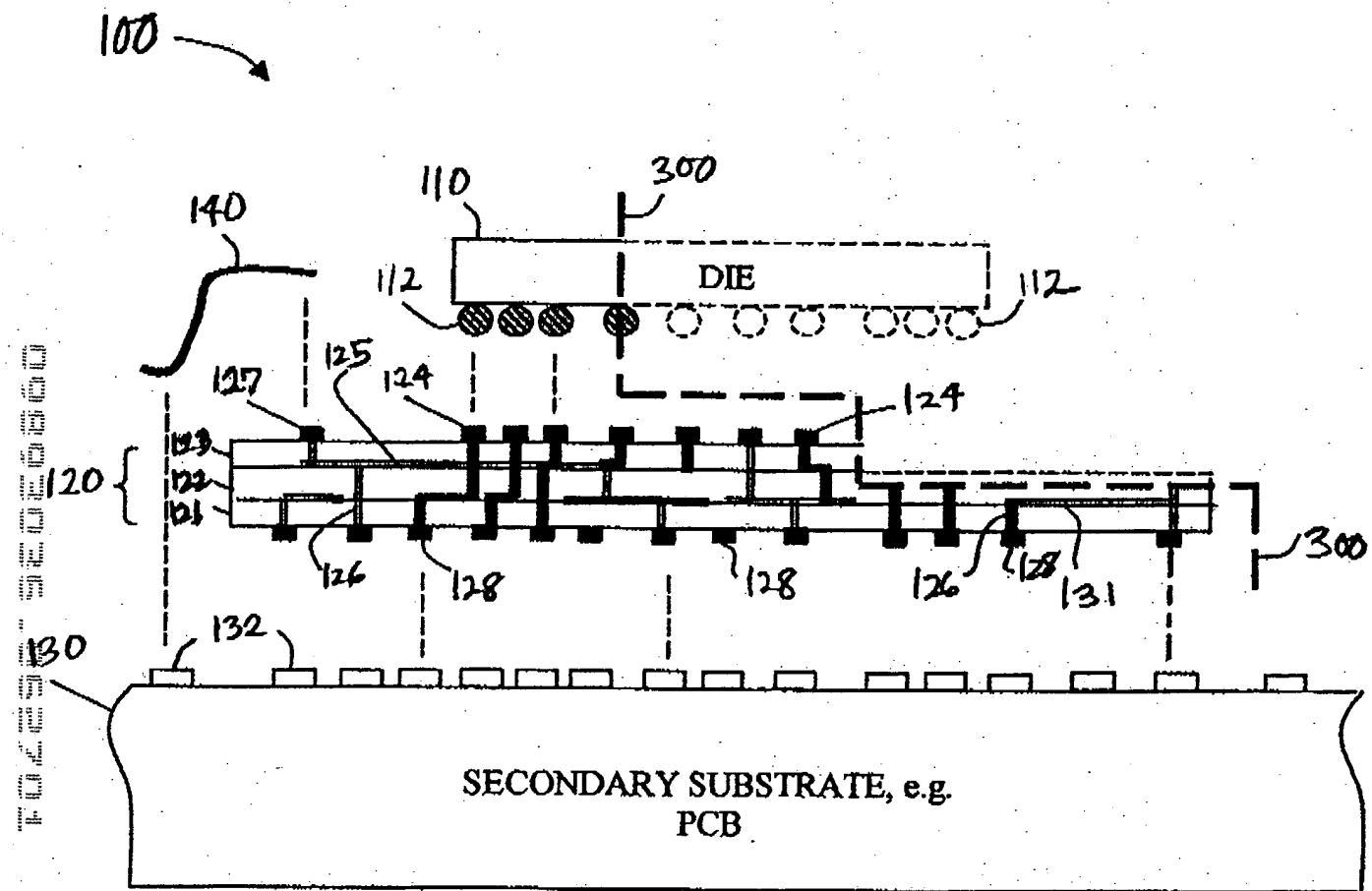


FIG. 3

FIG. 4

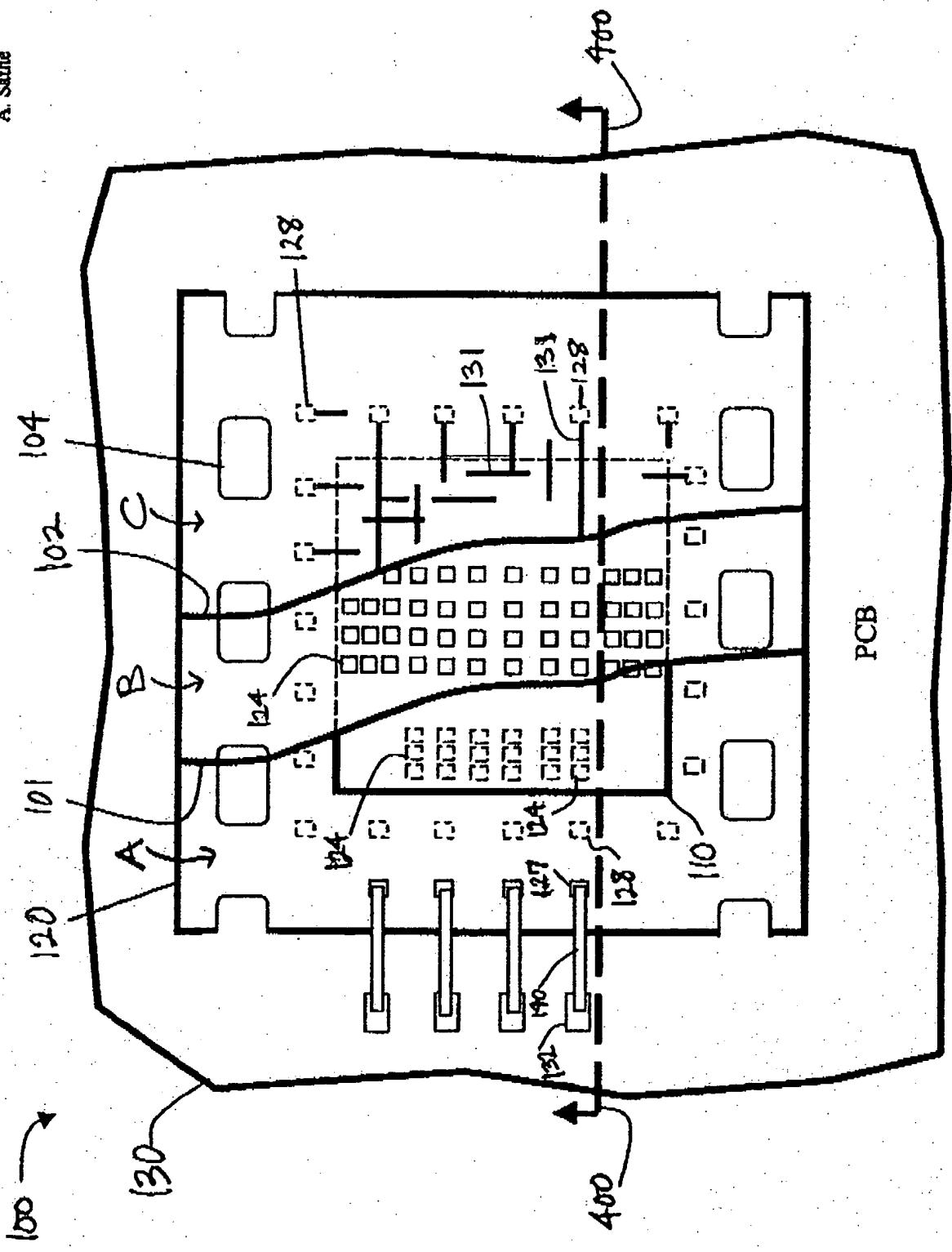


FIG. 4

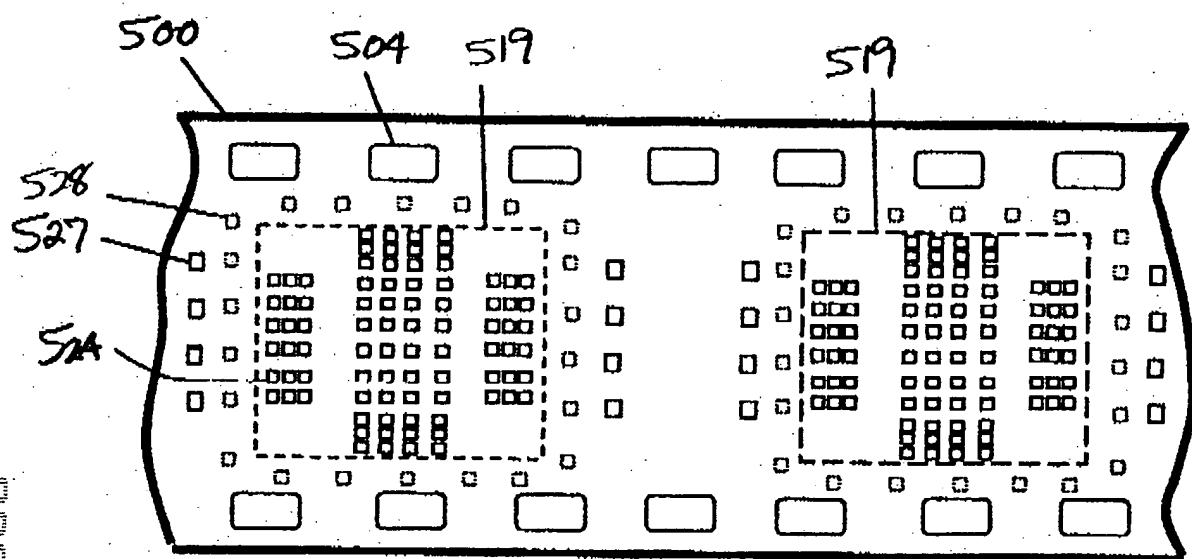


FIG. 5

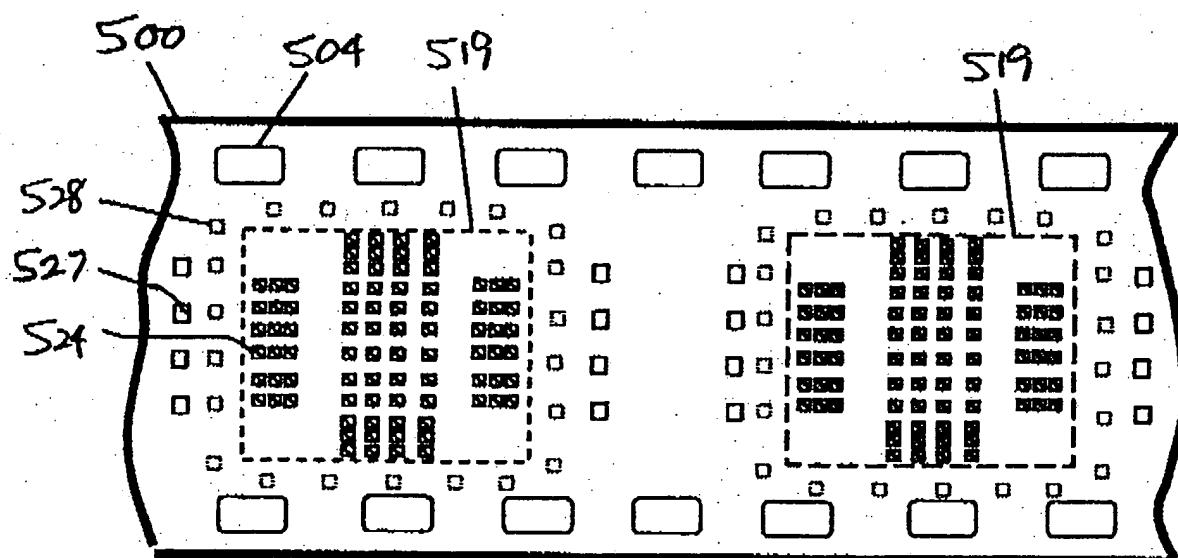


FIG. 6

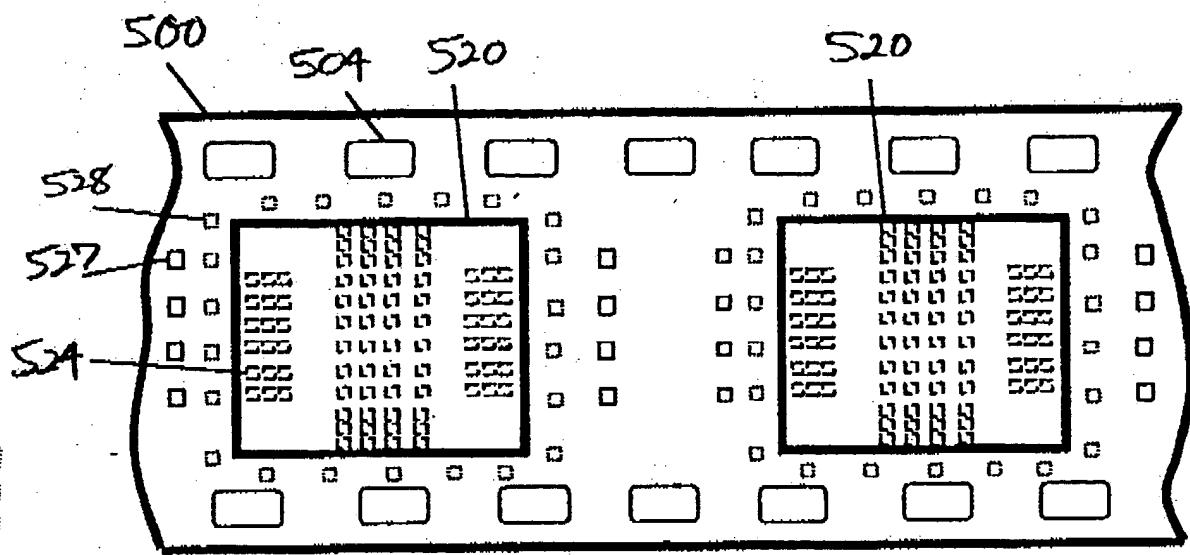


FIG. 7

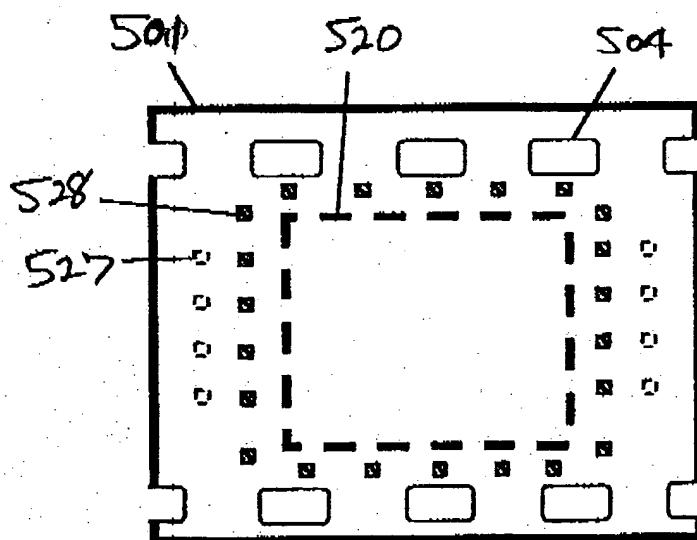


FIG. 8

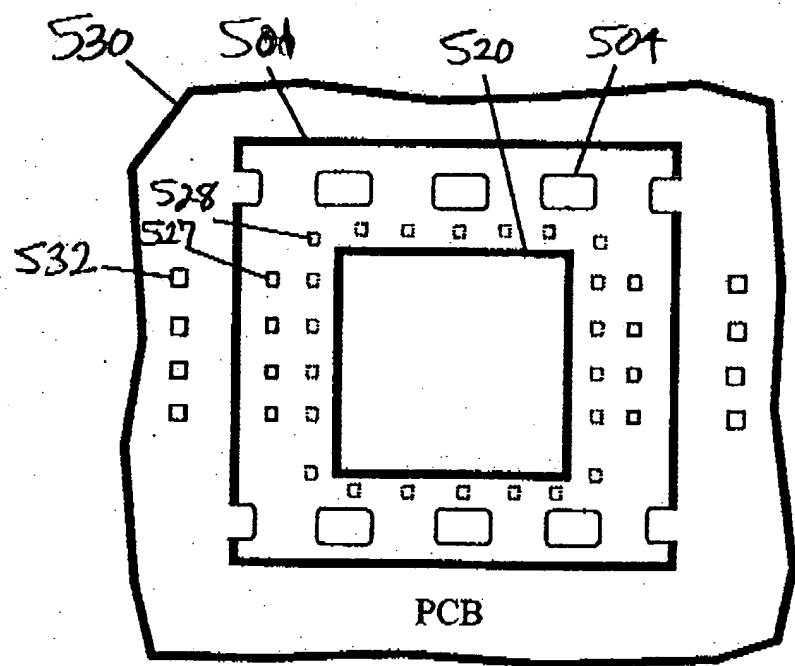


FIG. 9

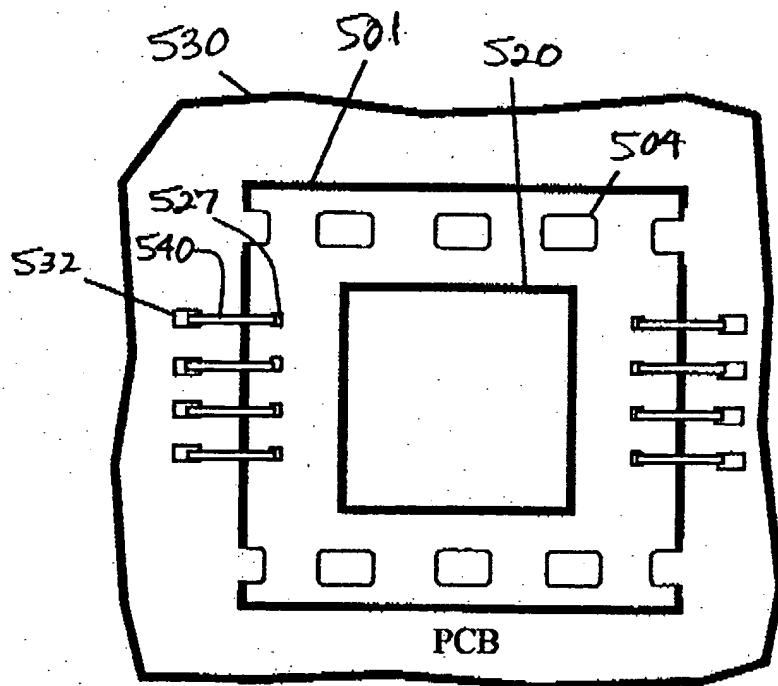


FIG. 10

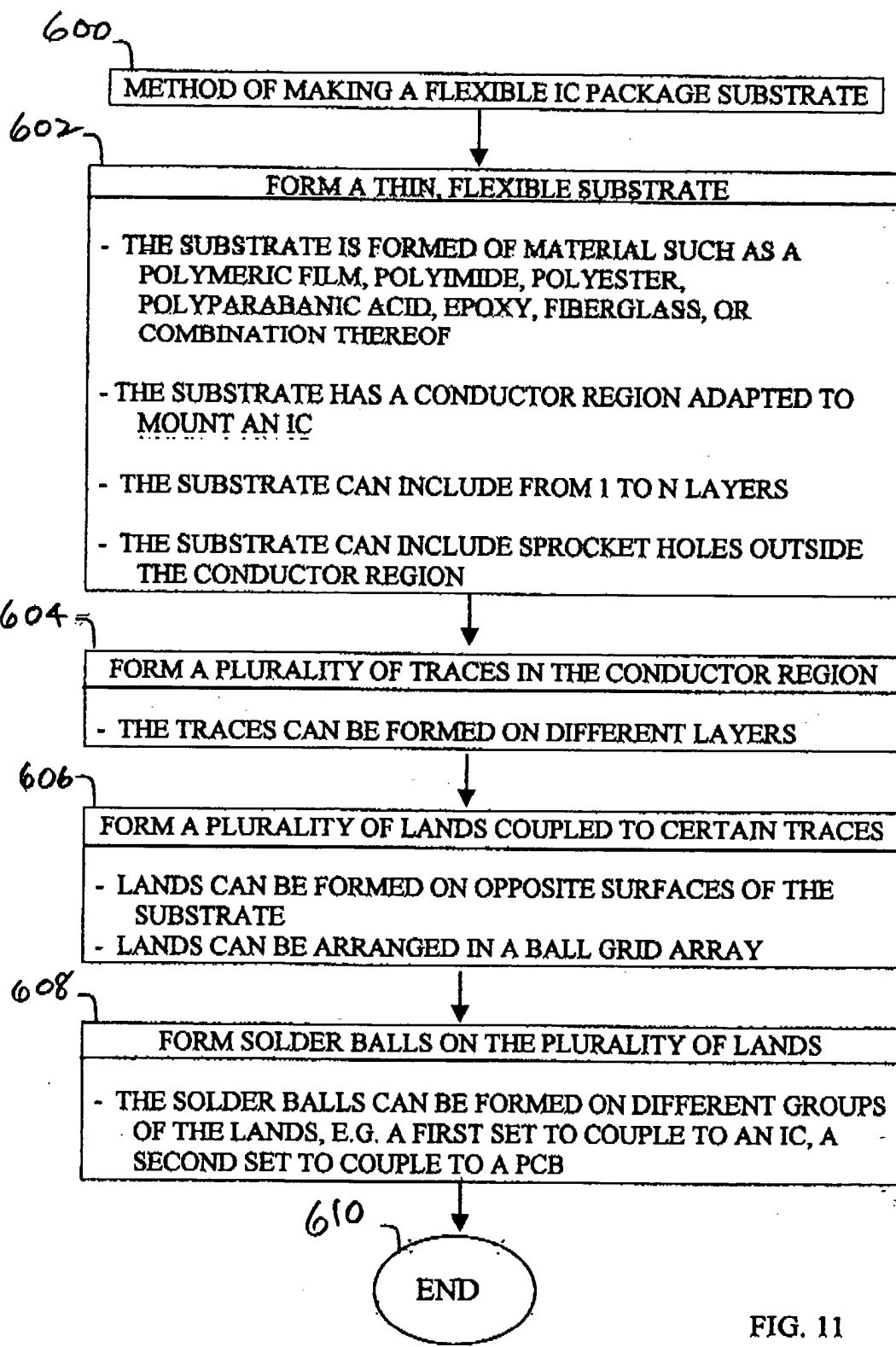


FIG. 11

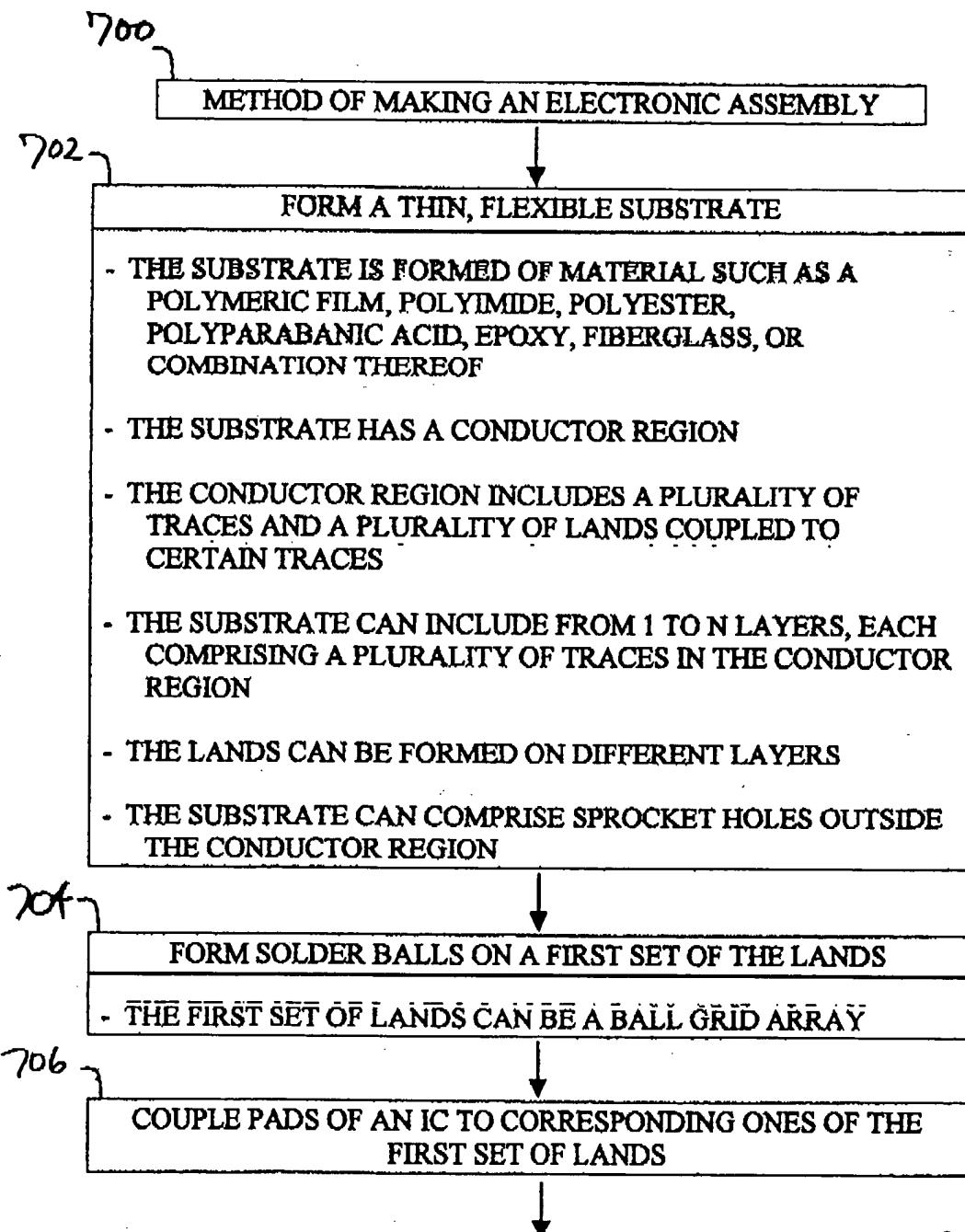


FIG. 12A

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**MOUNT THE SUBSTRATE ON AN ADDITIONAL SUBSTRATE, E.G.
A PCB**

EMPLOY EITHER OR BOTH OF THE FOLLOWING:

- USE BGA BETWEEN SUBSTRATE AND PCB
 - FORM SOLDER BALLS ON A SECOND SET OF THE LANDS
 - COUPLE ONES OF THE SECOND SET OF LANDS TO CORRESPONDING TERMINALS ON THE PCB
- USE LEADS BETWEEN SUBSTRATE AND PCB
 - COUPLE LEADS, E.G. WIRES, BETWEEN CORRESPONDING ONES OF A THIRD SET OF LANDS AND ADDITIONAL TERMINALS OF THE PCB



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END

FIG. 12B